300 V/µs

725 MHz

80 ns to 0.1%

4.75V to 32V

5 mA

<0.1%

<0.1°



## LM6165/LM6265/LM6365 High Speed Operational Amplifier

### **General Description**

The LM6165 family of high-speed amplifiers exhibits an excellent speed-power product in delivering 300 V/ $\mu$ s and 725 MHz GBW (stable for gains as low as +25) with only 5 mA of supply current. Further power savings and application convenience are possible by taking advantage of the wide dynamic range in operating supply voltage which extends all the way down to +5V.

These amplifiers are built with National's VIPTM (Vertically Integrated PNP) process which produces fast PNP transistors that are true complements to the already fast NPN devices. This advanced junction-isolated process delivers high speed performance without the need for complex and expensive dielectric isolation.

#### **Features**

■ High slew rate

■ High GBW product

Low supply currentFast settling

■ Low differential gain

■ Low differential phase

■ Wide supply range

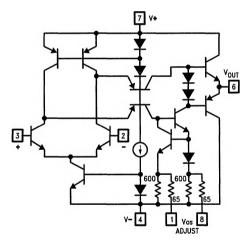
■ Stable with unlimited capacitive load

■ Well behaved; easy to apply

#### **Applications**

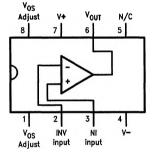
- Video amplifier
- Wide-bandwidth signal conditioning

## **Simplified Schematic**



#### TL/H/9152-3

## **Connection Diagram**



TL/H/9152-8

Order Number LM6165J or LM6265J See NS Package Number J08A

Order Number LM6365M See NS Package Number M08A

Order Number LM6265N or LM6365N See NS Package Number N08E

## **Absolute Maximum Ratings**

If Milltary/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V+ - V-) Differential Input Voltage (Note 8) ±8V

Common-Mode Voltage Range  $(V^+ - 0.7V)$  to  $(V^- - 7V)$ (Note 12)

Output Short Circuit to GND (Note 1) Continuous

Soldering Information Dual-In-Line Package (N, J)

Soldering (10 sec.) 260°C Small Outline Package (M)

Vapor Phase (60 sec.)

215°C Infrared (15 sec.) 220°C See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.

Storage Temp Range -65°C to +150°C

Max Junction Temperature (Note 2) 150°C ESD Tolerance (Notes 8 and 9) ±700V

## **Operating Ratings**

Temperature Range (Note 2)

LM6165  $-55^{\circ}\text{C} \le \text{T}_{\text{J}} \le +125^{\circ}\text{C}$ LM6265  $-25^{\circ}\text{C} \leq \text{T}_\text{J} \leq +85^{\circ}\text{C}$ LM6365  $0^{\circ}C \leq T_{J} \leq +70^{\circ}C$ 

4.75V to 32V Supply Voltage Range

#### DC Electrical Characteristics (Note 3)

	Conditions	Тур	LM6165		LM	<b>3265</b>	LM6365		
Parameter			Tested Limit	Design Limit	Tested Limit	Design Limit	Tested Limit	Design Limit	Units
			(Note 4)	(Note 5)	(Note 4)	(Note 5)	(Note 4)	(Note 5)	
Input Offset Voltage		1	3 <b>4</b>		3	4	6	7	mV max
Input Offset Voltage Average Drift		3							μV/°C
Input Bias Current		2.5	3 <b>6</b>		3	5	5	6	μA max
Input Offset Current		150	350 <b>800</b>		350	600	1500	1900	na max
Input Offset Current Average Drift		0.3							nA/°C
Input Resistance	Differential	20							kΩ
Input Capacitance		6.0					-()-		рF
Large Signal Voltage Gain	$V_{OUT} = \pm 10V$ , $R_L = 2 k\Omega$ (Note 11)	10.5	7.5 <b>5.0</b>		7.5	6.0	5.5	5.0	V/mV min
	$R_L = 10  k\Omega$	38							
Input Common-Mode Voltage Range	Supply = ±15V	+14.0	+13.9 +13.8		+ 13.9	+ 13.8	+ 13.8	+ 13.7	V min
		-13.6	-13.4 -13.2	0	-13.4	-13.2	-13.3	- 13.2	V min
	Supply = +5V (Note 6)	4.0	3.9 <b>3.8</b>		3.9	3.8	3.8	3.7	V min
		1.4	1.6 <b>1.8</b>		1.6	1.8	1.7	1.8	V max
Common-Mode Rejection Ratio	-10V ≤ V <sub>CM</sub> ≤ +10V	102	88 <b>82</b>		88	84	80	78	dB min
Power Supply Rejection Ratio	±10V ≤ V± ≤ ±16V	104	88 <b>82</b>		88	84	80	78	dB min
Output Voltage Swing	Supply = $\pm 15V$ and R <sub>L</sub> = $2k\Omega$	+ 14.2	+ 13.5 + <b>13.3</b>		+ 13.5	+ 13.3	+ 13.4	+ 13.3	V min
		-13.4	-13.0 - <b>12.7</b>		-13.0	-12.8	-12.9	-12.8	V min

#### DC Electrical Characteristics (Note 3) (Continued)

			LM6165		LM6265		LM6365		
Parameter	Conditions	Тур	Tested Limit	Design Limit	Tested Limit	Design Limit	Tested Limit	Design Limit	Units
			(Note 4)	(Note 5)	(Note 4)	(Note 5)	(Note 4)	(Note 5)	
Output Voltage Swing	Supply = $+5V$ and R <sub>L</sub> = $2 k\Omega$ (Note 6)	4.2	3.5 <b>3.3</b>		3.5	3.3	3.4	3.3	V min
	_	1.3	1.7 <b>2.0</b>		1.7	1.9	1.8	1.9	V max
Output Short Circuit Current	Source	65	30 <b>20</b>		30	25	30	25	mA min
	Sink	65	30 <b>20</b>		30	25	30	25	mA min
Supply Current		5.0	6.5 <b>6.8</b>		6.5	6.7	6.8	6.9	mA max

## **AC Electrical Characteristics** (Notes 3 & 7)

Parameter	Conditions	Тур	LM6165		LM6265		LM6365		
			Tested Limit	Design Limit	Tested Limit	Design Limit	Tested Limit	Design Limit (Note 5)	Units
			(Note 4)	(Note 5)	(Note 4)	(Note 5)	(Note 4)		
Gain-Bandwidth Product	@ F = 20 MHz	725	575 <b>350</b>		575	425	500	400	MHz min
	Supply = ±5V	500							
Slew Rate	$A_V = +25 \text{ (Note 10)}$	300	200 <b>180</b>		200	180	200	180	V/μs min
	Supply = ±5V	200							
Power Bandwidth	V <sub>OUT</sub> = 20 V <sub>PP</sub>	4.5		_					MHz
Setting Time	10V Step to 0.1% $A_V = -25$ , $R_L = 2 k\Omega$	80							ns
Phase Margin	$A_V = +25$	45							Deg
Differential Gain	NTSC, A <sub>V</sub> = +25	<0.1							%
Differential Phase	NTSC, A <sub>V</sub> = +25	<0.1							Deg
Input Noise Voltage	F = 10 kHz	5							nV/√Hz
Input Noise Current	F = 10 kHz	1.5			}				pA/√Hz

Note 1: Continuous short-circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C.

Note 2: The typical junction-to-ambient thermal resistance of the molded plastic DIP (N) is 105°C/Watt, and the molded plastic SO (M) package is 155°C/Watt, and the cerdip (J) package is 125°C/Watt. All numbers apply for packages soldered directly into a printed circuit board.

Note 3: Unless otherwise specified, all limits guaranteed for  $T_a = T_j = 25^{\circ}\text{C}$  with supply voltage =  $\pm 15\text{V}$ ,  $V_{CM} = 0\text{V}$ , and  $R_L \ge 100 \text{ k}\Omega$ . Boldface limits apply over the range listed under "Operating Temperature Range".

Note 4: All limits guaranteed at room temperature (standard type face) and at temperature extremes (bold type face). All limits are 100% production tested.

Note 5: All limits guaranteed at room temperature (standard type face) and at temperature extremes (bold type face). All limits are guaranteed via correlation using standard Statistical Quality Control (SQC) methods.

Note 6: For single supply operation, the following conditions apply:  $V_+ = 5V$ ,  $V_- = 0V$ ,  $V_{CM} = 2.5C$ ,  $V_{OUT} = 2.5V$ . Pin 1 & Pin 8 ( $V_{OS}$  Adjust) are each connected to Pin 4 ( $V_-$ ) to realize maximum output swing. This connection will degrade  $V_{OS}$ .

Note 7:  $C_t \le 5 pF$ .

Note 8: In order to achieve optimum AC performance, the input stage was designed without protective clamps. Exeeding the maximum differential input voltage results in reverse breakdown of the base-emitter junction of one of the input transistors and probable degradation of the input parameters (especially V<sub>OS</sub>, I<sub>OS</sub>, and Noise)

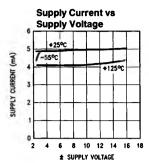
Note 9: The average voltage that the weakest pin combinations (those involving Pin 2 or Pin 3) can withstand and still conform to the datasheet limits. The test circuit used consists of the human body model of 100 pF in series with 1500 $\Omega$ .

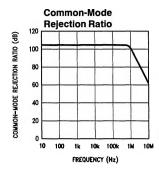
Note 10:  $V_{IN} = 0.7V$  step. For supply =  $\pm 5V$ ,  $V_{IN} = 0.2V$  step.

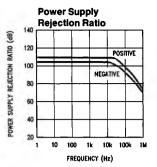
Note 11: Voltage Gain is the total output swing (20V) divided by the input signal required to produce that swing.

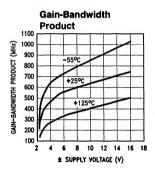
Note 12: The voltage between V+ and either input pin must not exceed 36V.

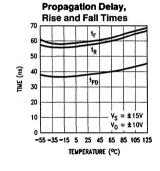
## Typical Performance Characteristics $R_L = 10 \text{ k}\Omega$ , $T_A = 25^{\circ}\text{C}$ unless otherwise specified

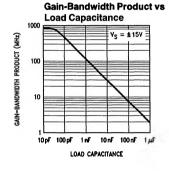


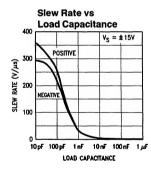


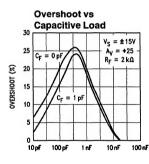


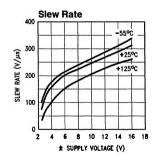


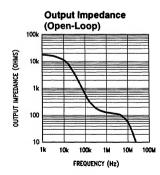


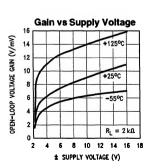










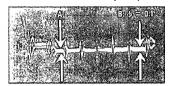


# Typical Performance Characteristics (Continued) $R_L=10~k\Omega,\,T_A=25^{\circ}C$ unless otherwise specified

#### Differential Gain (Note)



#### Differential Phase (Note)

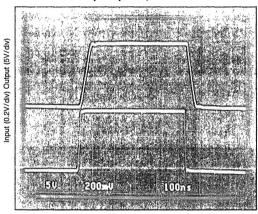


TL/H/9152-7

Note: Differential gain and differential phase measured for four series LM6365 op amps configured with gain of +25 (each output attenuated by 96%), in series with an LM6321 buffer. Error added by LM6321 is negligible. Test performed using Tektronix Type 520 NTSC test system.

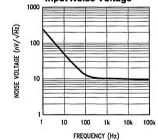
TL/H/9152-6

Step Response; Av = +1



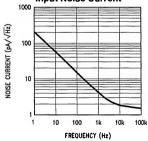
TL/H/9152-1

Input Noise Voltage

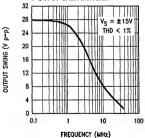


**Input Noise Current** 

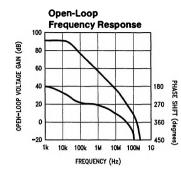
TIME (50 (ns/div)

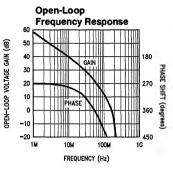


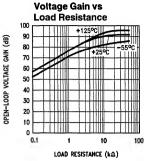
**Power Bandwidth** 

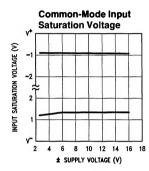


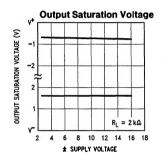
# Typical Performance Characteristics (Continued) $R_L=10~k\Omega,~T_A=25^{\circ}C$ unless otherwise specified

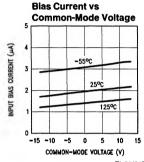












#### **Applications Tips**

The LM6365 has no frequency compensation, but is stable for gains of 25 or greater (over the specified ranges of temperature, power supply voltage, and load). The LM6365 and LM6364, specified in separate datasheets, are compensated versions of the LM6365. The LM6361 is unity-gain stable, while the LM6364 is stable for gains as low as 5. The LM6361, and LM6364 have the same high slew rate as the LM6365, typically 300 V/ $\mu$ s.

To use the LM6365 for gains less than 25, a series resistorcapacitor network should be added between the input pins (as shown in the Typical Applications, Noise Gain Compensation) so that the high-frequency noise gain rises to at least 25.

Power supply bypassing will improve stability and transient response of the LM6365, and is recommended for every

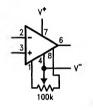
design. 0.01  $\mu F$  to 0.1  $\mu F$  ceramic capacitors should be used (from each supply "rail" to ground); an additional 2.2  $\mu F$  to 10  $\mu F$  (tantalum) may be required for extra noise reduction.

Keep all leads short to reduce stray capacitance and lead inductance, and make sure ground paths are low-impedance, especially where heavier currents will be flowing. Stray capacitance in the circuit layout can cause signal coupling between adjacent nodes, and can cause circuit gain to unintentionally vary with frequency.

Breadboarded circuits will work best if they are built using generic PC boards with a good ground plane. If the op amps are used with sockets, as opposed to being soldered into the circuit, the additional input capacitance may degrade circuit performance.

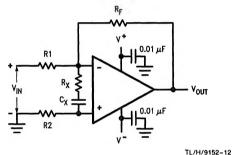
#### **Typical Applications**

#### Offset Voltage Adjustment



TL/H/9152-11

#### **Noise-Gain Compensation**



25 MHz

 $R_XC_X \ge \frac{1}{2}\pi \cdot 25 \text{ MHz}$  $[R1 + R_F (1 + R1/R2)] = 25 R_X$ 

## 1 MHz Voltage-to-Frequency Converter $(f_{OUT} = 1 \text{ MHz for } V_{IN} = 10V)$

